

N-channel 650 V, 0.093 Ω typ., 32 A MDmesh™ DM2 Power MOSFET in a TO-247 long leads package

Datasheet - production data

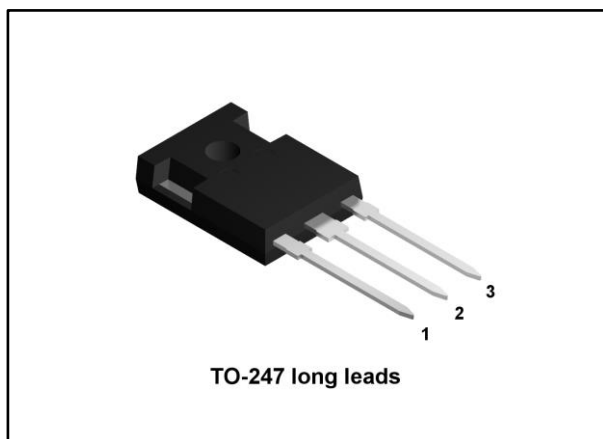
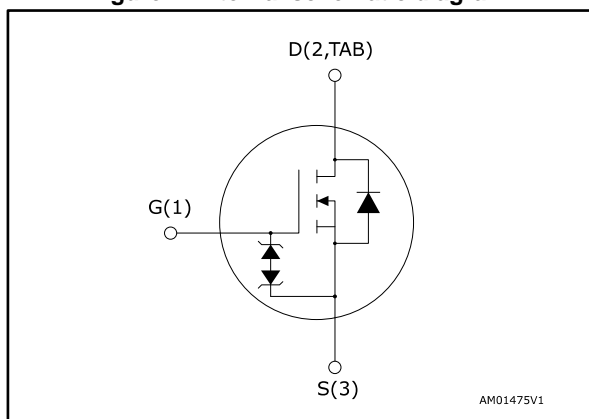


Figure 1: Internal schematic diagram



Features

| Order code | V _{DS} | R _{DS(on)} max. | I _D | P _{TOT} |
|--------------|-----------------|-----------------------------|----------------|------------------|
| STWA35N65DM2 | 650 V | 0.110 Ω | 32 A | 250 W |

- Fast-recovery body diode
- Extremely low gate charge and input capacitance
- Low on-resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

Applications

- Switching applications

Description

This high voltage N-channel Power MOSFET is part of the MDmesh™ DM2 fast recovery diode series. It offers very low recovery charge (Q_{rr}) and time (t_{rr}) combined with low $R_{DS(on)}$, rendering it suitable for the most demanding high efficiency converters and ideal for bridge topologies and ZVS phase-shift converters.

Table 1: Device summary

| Order code | Marking | Package | Packing |
|--------------|----------|-------------------|---------|
| STWA35N65DM2 | 35N65DM2 | TO-247 long leads | Tube |

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1 Electrical ratings

Table 2: Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|--|------------|--------------------|
| V_{GS} | Gate-source voltage | ± 25 | V |
| I_D | Drain current (continuous) at $T_{case} = 25\text{ }^{\circ}\text{C}$ | 32 | A |
| | Drain current (continuous) at $T_{case} = 100\text{ }^{\circ}\text{C}$ | 20 | |
| $I_{DM}^{(1)}$ | Drain current (pulsed) | 90 | A |
| P_{TOT} | Total dissipation at $T_{case} = 25\text{ }^{\circ}\text{C}$ | 250 | W |
| $dv/dt^{(2)}$ | Peak diode recovery voltage slope | 50 | V/ns |
| $dv/dt^{(3)}$ | MOSFET dv/dt ruggedness | 50 | |
| T_{stg} | Storage temperature range | -55 to 150 | $^{\circ}\text{C}$ |
| T_j | Operating junction temperature range | | |

Notes:

(1) Pulse width is limited by safe operating area.

(2) $I_{SD} \leq 32\text{ A}$, $di/dt = 900\text{ A}/\mu\text{s}$, $V_{DS\text{ peak}} < V_{(BR)DSS}$, $V_{DD} = 80\% V_{(BR)DSS}$

(3) $V_{DS} \leq 520\text{ V}$

Table 3: Thermal data

| Symbol | Parameter | Value | Unit |
|----------------|-------------------------------------|-------|-----------------------------|
| $R_{thj-case}$ | Thermal resistance junction-case | 0.5 | $^{\circ}\text{C}/\text{W}$ |
| $R_{thj-amb}$ | Thermal resistance junction-ambient | 50 | |

Table 4: Avalanche characteristics

| Symbol | Parameter | Value | Unit |
|----------------|---|-------|------|
| I_{AR} | Avalanche current, repetitive or non-repetitive | 4 | A |
| $E_{AS}^{(1)}$ | Single pulse avalanche energy | 1150 | mJ |

Notes:

(1) Starting $T_j = 25\text{ }^{\circ}\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$.

2 Electrical characteristics

(T_{case} = 25 °C unless otherwise specified)

Table 5: Static

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|----------------------|-----------------------------------|---|------|-------|-------|------|
| V _{(BR)DSS} | Drain-source breakdown voltage | V _{GS} = 0 V, I _D = 1 mA | 650 | | | V |
| I _{DSS} | Zero gate voltage drain current | V _{GS} = 0 V, V _{DS} = 650 V | | | 1 | μA |
| | | V _{GS} = 0 V, V _{DS} = 650 V, T _{case} = 125 °C ⁽¹⁾ | | | 100 | |
| I _{GSS} | Gate-body leakage current | V _{DS} = 0 V, V _{GS} = ±25 V | | | ±5 | μA |
| V _{GS(th)} | Gate threshold voltage | V _{DS} = V _{GS} , I _D = 250 μA | 3 | 4 | 5 | V |
| R _{DS(on)} | Static drain-source on-resistance | V _{GS} = 10 V, I _D = 16 A | | 0.093 | 0.110 | Ω |

Notes:

⁽¹⁾Defined by design, not subject to production test.

Table 6: Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|-------------------------------|---|------|------|------|------|
| C _{iss} | Input capacitance | V _{DS} = 100 V, f = 1 MHz, V _{GS} = 0 V | - | 2540 | - | pF |
| C _{oss} | Output capacitance | | - | 115 | - | |
| C _{rss} | Reverse transfer capacitance | | - | 2.5 | - | |
| C _{oss eq.} ⁽¹⁾ | Equivalent output capacitance | V _{DS} = 0 to 520 V, V _{GS} = 0 V | - | 204 | - | pF |
| R _G | Intrinsic gate resistance | f = 1 MHz, I _D = 0 A | - | 4.2 | - | Ω |
| Q _g | Total gate charge | V _{DD} = 520 V, I _D = 32 A, V _{GS} = 0 to 10 V (see Figure 15: "Test circuit for gate charge behavior") | - | 56.3 | - | nC |
| Q _{gs} | Gate-source charge | | - | 12.7 | - | |
| Q _{gd} | Gate-drain charge | | - | 27.6 | - | |

Notes:

⁽¹⁾C_{oss eq.} is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.

Table 7: Switching times

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------------|---------------------|---|------|------|------|------|
| t _{d(on)} | Turn-on delay time | V _{DD} = 325 V, I _D = 16 A, R _G = 4.7 Ω, V _{GS} = 10 V (see Figure 14: "Test circuit for resistive load switching times" and Figure 19: "Switching time waveform") | - | 23.4 | - | ns |
| t _r | Rise time | | - | 23 | - | |
| t _{d(off)} | Turn-off delay time | | - | 72 | - | |
| t _f | Fall time | | - | 10.4 | - | |

Table 8: Source-drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------------|-------------------------------|--|------|------|------|---------------|
| I_{SD} | Source-drain current | | - | | 32 | A |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | - | | 90 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $V_{GS} = 0\text{ V}$, $I_{SD} = 32\text{ A}$ | - | | 1.6 | V |
| t_{rr} | Reverse recovery time | $I_{SD} = 32\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$ (see Figure 16: "Test circuit for inductive load switching and diode recovery times") | - | 100 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 0.42 | | μC |
| I_{RRM} | Reverse recovery current | | - | 8.4 | | A |
| t_{rr} | Reverse recovery time | $I_{SD} = 32\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$, $T_j = 150\text{ }^\circ\text{C}$ (see Figure 16: "Test circuit for inductive load switching and diode recovery times") | - | 205 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 1.8 | | μC |
| I_{RRM} | Reverse recovery current | | - | 17.6 | | A |

Notes:

⁽¹⁾Pulse width is limited by safe operating area.

⁽²⁾Pulse test: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2: Safe operating area

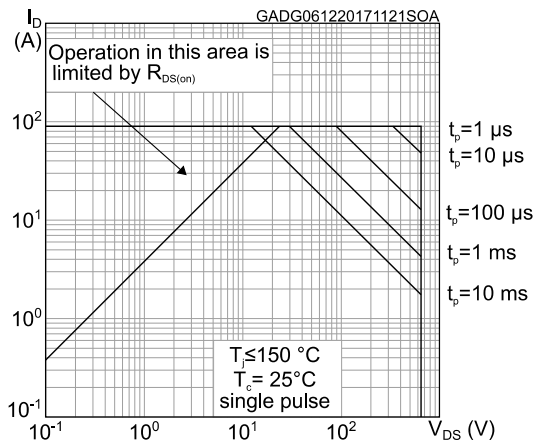


Figure 3: Thermal impedance

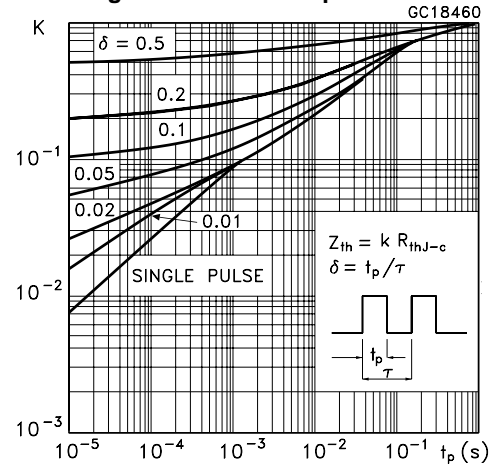


Figure 4: Output characteristics

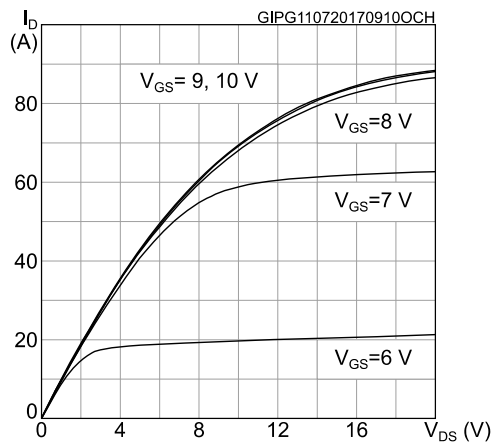


Figure 5: Transfer characteristics

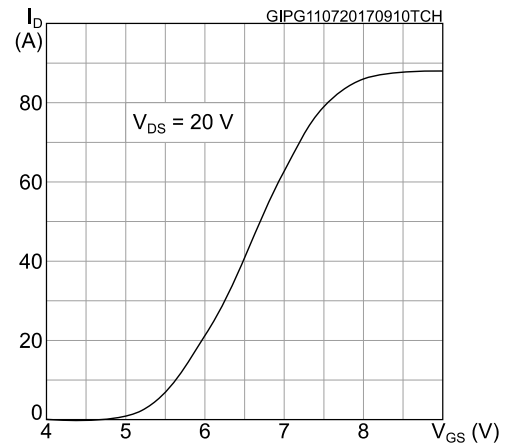


Figure 6: Gate charge vs gate-source voltage

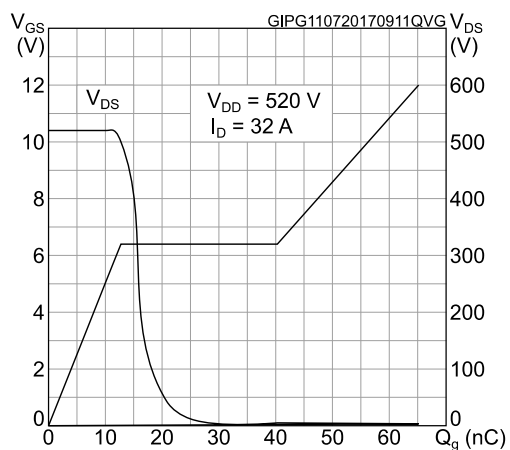


Figure 7: Static drain-source on-resistance

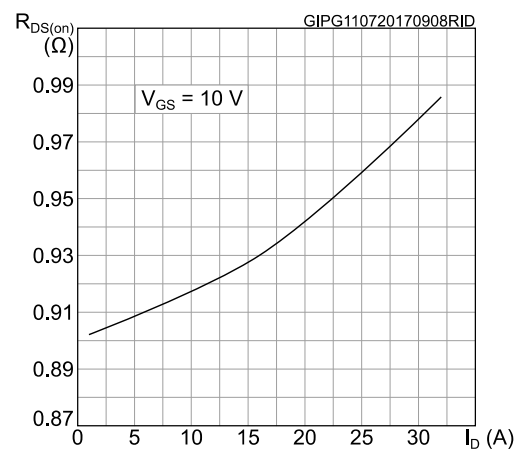


Figure 8: Capacitance variations

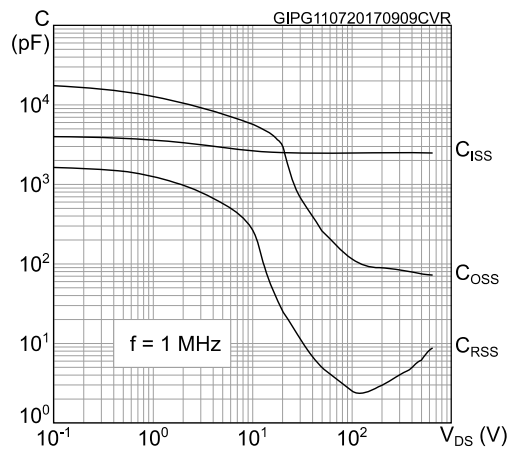


Figure 9: Normalized gate threshold voltage vs temperature

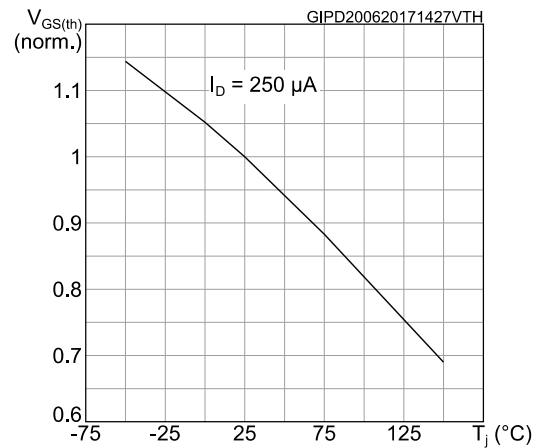


Figure 10: Normalized on-resistance vs temperature

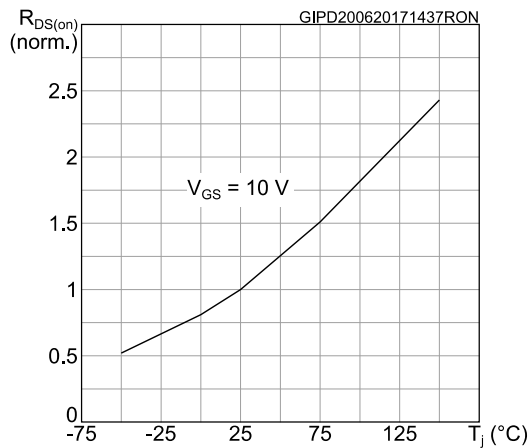
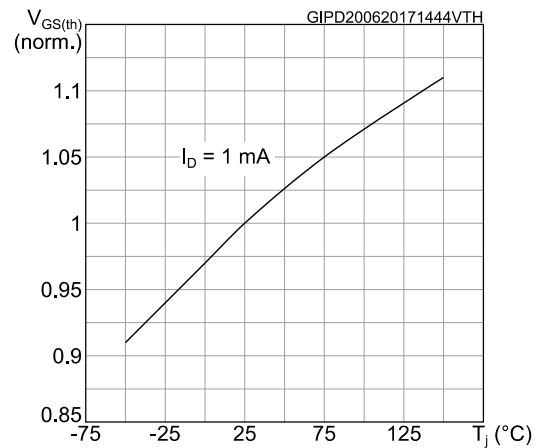
Figure 11: Normalized $V_{(BR)DSS}$ vs temperature

Figure 12: Output capacitance stored energy

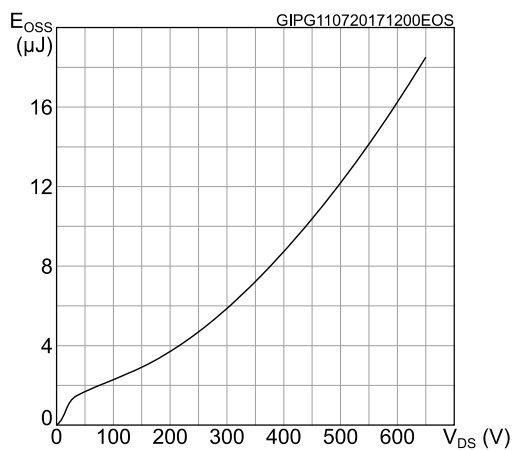
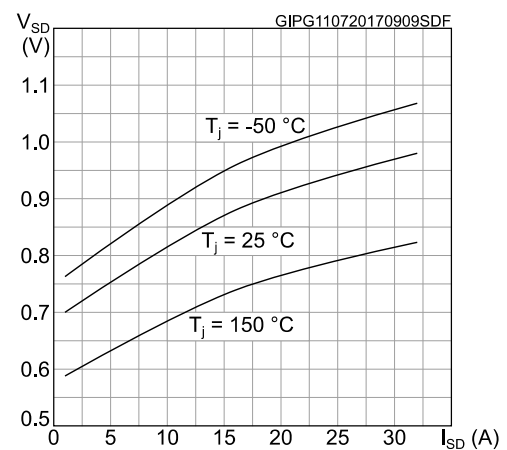
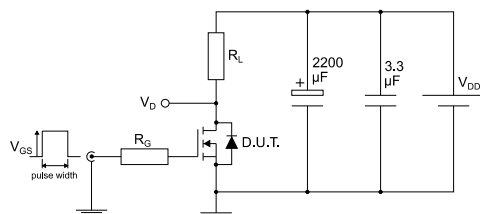


Figure 13: Source-drain diode forward characteristics



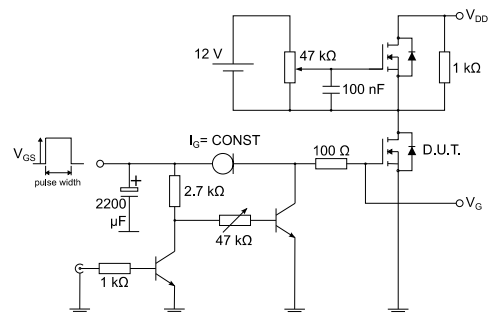
3 Test circuits

Figure 14: Test circuit for resistive load switching times



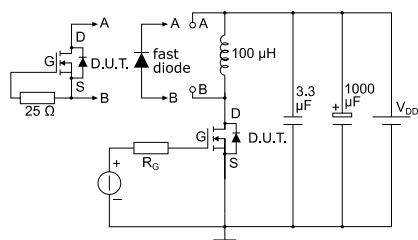
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Figure 15: Test circuit for gate charge behavior



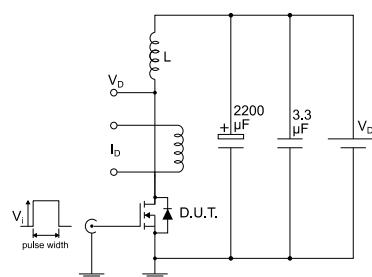
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Figure 16: Test circuit for inductive load switching and diode recovery times



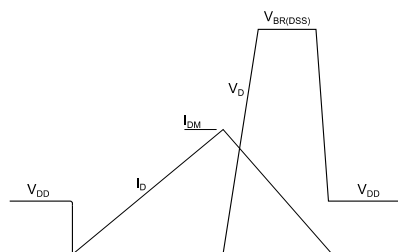
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Figure 17: Unclamped inductive load test circuit



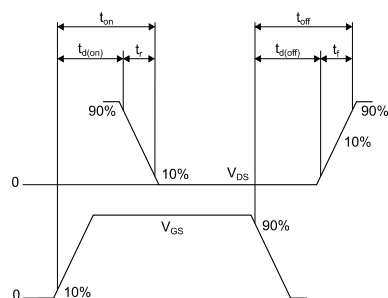
AM01471v1

Figure 18: Unclamped inductive waveform



AM01472v1

Figure 19: Switching time waveform



AM01473v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 TO-247 long leads package information

Figure 20: TO-247 long leads package outline

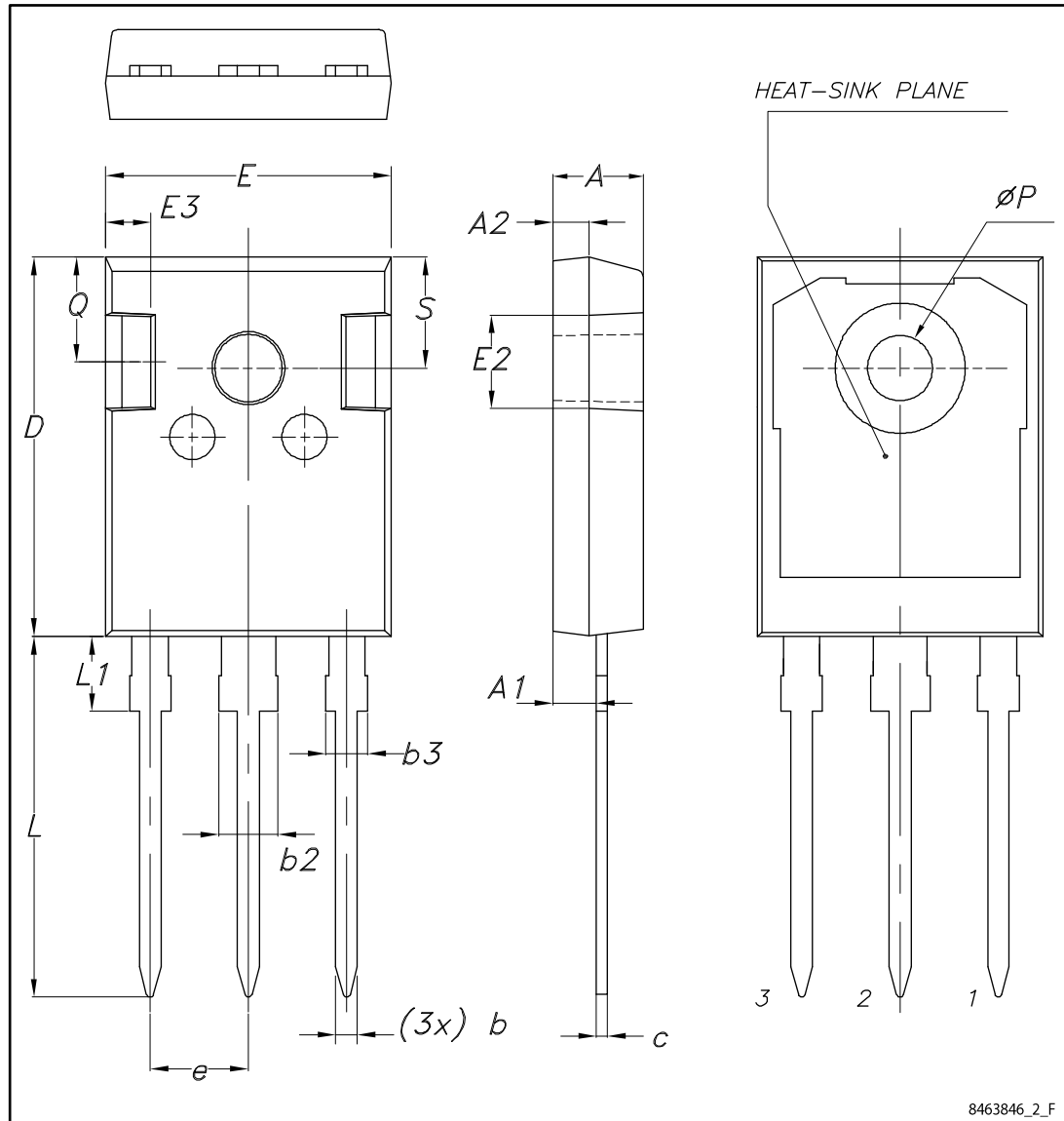


Table 9: TO-247 long leads package mechanical data

| Dim. | mm | | |
|------|-------|-------|-------|
| | Min. | Typ. | Max. |
| A | 4.90 | 5.00 | 5.10 |
| A1 | 2.31 | 2.41 | 2.51 |
| A2 | 1.90 | 2.00 | 2.10 |
| b | 1.16 | | 1.26 |
| b2 | | | 3.25 |
| b3 | | | 2.25 |
| c | 0.59 | | 0.66 |
| D | 20.90 | 21.00 | 21.10 |
| E | 15.70 | 15.80 | 15.90 |
| E2 | 4.90 | 5.00 | 5.10 |
| E3 | 2.40 | 2.50 | 2.60 |
| e | 5.34 | 5.44 | 5.54 |
| L | 19.80 | 19.92 | 20.10 |
| L1 | | | 4.30 |
| P | 3.50 | 3.60 | 3.70 |
| Q | 5.60 | | 6.00 |
| S | 6.05 | 6.15 | 6.25 |

5 Revision history

Table 10: Document revision history

| Date | Revision | Changes |
|-------------|----------|---|
| 21-Jul-2017 | 1 | Initial release |
| 06-Dec-2017 | 2 | Document status changed from preliminary to production data. Updated Table 2: "Absolute maximum ratings" and Table 8: "Source-drain diode" . Updated Section 2.1: "Electrical characteristics (curves)" . Updated Figure 2: "Safe operating area" . Minor text changes. |

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